



Title of Change:	Planned assembly and test capacity expansion for DFN12 3.0x1.35 mm including SNUF6401MNT1G DFN package at ON Semiconductor's factory in Tarlac, Philippines.
Proposed Changed Material First Ship Date:	31 August 2019 <i>or earlier upon customer approval.</i>
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.
Product Category:	Active components – Discrete components
Contact information:	Contact your local ON Semiconductor Sales Office or < Mike.Begonia@onsemi.com >
Samples:	Contact your local ON Semiconductor Sales Office to place sample order or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 45 days after publication of this change notification.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Phine.Guevarra@onsemi.com >
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 12 months prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >.
Change Category	Type of Change
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Process – Assembly	Change of leadframe base material
Process – Assembly	Manufacturing site transfer
Process – Assembly	Change of mold compound

Description and Purpose:

This PCN announces to customers of its plan to add Operation Site of ON Semiconductor Tarlac, Philippines for DFN12 3.0x1.35, 0.5P mm 6-Channel EMI Filter with Integrated ESD Protection from existing Seremban Plant S1 in Malaysia. The Philippines internal facility is certified with ISO/TS 16949:2009 and is currently running production for XFN package.

These products will continue being Pb-free, Halide free and RoHS compliant. Qualification tests are designed to show that the reliability of the transferred devices will continue to meet or exceed ON Semiconductor standards.

	Before Change Description	After Change Description
LeadFrame	Selective Ag Plated LF	PPF Lead Frame
Die Attach	DA AB8008 CON 10cc	SAME
Bond Wire	0.8mil Au Wire	SAME
Mold Compound	EMEG760 14x6.5	EME G770 27x10cc
Assembly Site	SBN S1 Malaysia	OSPI Tarlac Philippines
Test Site	SBN S1 Malaysia	OSPI Tarlac Philippines



	From	To
Product marking change	Line1:64 Line2:01 Line3:M Where: M single digit month code	Line1:64 Line2:01 Line3:MI Where: M single digit month code + vertical line corresponding site code

Reason / Motivation for Change:

- Second sourcing for DFN 12 3*1.35 mm which includes automotive SNUF6401MNT1G.

Anticipated impact on fit, form, function, reliability, product safety or manufacturability:

The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.

No anticipated impacts.

Sites Affected:

ON Semiconductor Sites:
ON Seremban, Malaysia
ON Tarlac City, Philippines

External Foundry/Subcon Sites:
None

Marking of Parts/ Traceability of Change:

Additional vertical line on month date code (MI) for OSPI Tarlac bui

Reliability Data Summary:

QV DEVICE NAME: SNUF6401MNT1G

PACKAGE: DFN12 3.0x1.35, 0.5P

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Tj = Max rate Tj for device, bias = 100% of rated V (for automotive)	2016 hrs
HTSL	JESD22-A103	Ta =Max rate storage temp for device for 1008 hrs	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C max, Ton=Toff is pkg dependent	15000 cyc
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	2000 cyc
HAST	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
uHAST	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
PC	J-STD-020 JESD-A113	IR reflow at 245C or 260C (pkg dependant)	
RSH	JESD22- B106	Ta=265C 10 sec dwell B106	

Electrical Characteristic Summary:

Available upon request

List of Affected Parts:

Current Part Number	New Part Number	Qualification Vehicle
SNUF6401MNT1G	SNUF6401MNT1G	SNUF6401MNT1G